

General Description:

105N15 , the silicon N-channel Enhanced VDMOSFETs, is obtained by advanced Trench Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is TO-220AB, which accords with the RoHS standard.

Features:

- | Fast Switching
- | Low ON Resistance
- | Low Gate Charge
- | Low Reverse transfer capacitances(Typical:220.2pF)
- | 100% Single Pulse avalanche energy Test

Applications:

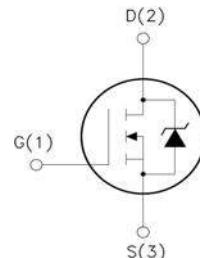
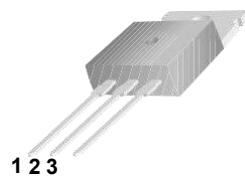
Power switch circuit of adaptor and charger.

Absolute ($T_J = 25^\circ\text{C}$ unless otherwise specified):

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	150	V
I_D	Continuous Drain Current $T_C = 25^\circ\text{C}$	105	A
	Continuous Drain Current $T_C = 100^\circ\text{C}$	72	A
I_{DM}^{a1}	Pulsed Drain Current $T_C = 25^\circ\text{C}$	420	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}^{a2}	Single Pulse Avalanche Energy	925	mJ
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	312.5	W
	Derating Factor above 25°C	2.5	W/ $^\circ\text{C}$
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$
T_L	Maximum Temperature for Soldering	300	$^\circ\text{C}$

V_{DSS}	150	V
I_D	105	A
$P_D(T_C=25^\circ\text{C})$	312.5	W
$R_{DS(ON)}^{\text{Typ}}$	9.8	$\text{m}\Omega$

TO-220AB



- 1.Gate (G)
2.Drain (D)
3.Source (S)

Electrical Characteristics (T_J= 25°C unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	150	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =150V, V _{GS} = 0V, T _J = 25°C	--	--	1	μA
		V _{DS} =120V, V _{GS} = 0V, T _J = 125°C	--	--	100	μA
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =+20V	--	--	100	nA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =-20V	--	--	-100	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _{DS(ON)}	Drain-to-Source On-Resistance	V _{GS} =10V, I _D =75A	--	9.8	12	mΩ
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	3.0	--	5.0	V
Pulse width t _p ≤300μs, δ ≤2%						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	--	2.3	--	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =50V f=1.0MHz	--	7400	--	pF
C _{oss}	Output Capacitance		--	488.6	--	
C _{rss}	Reverse Transfer Capacitance		--	220.2	--	

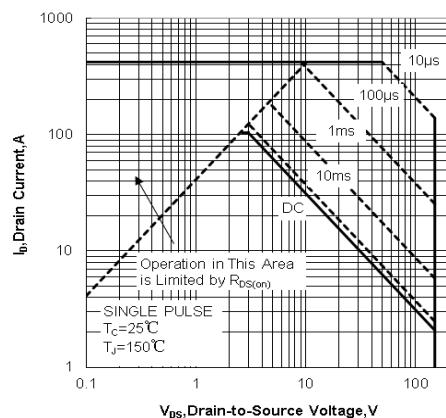
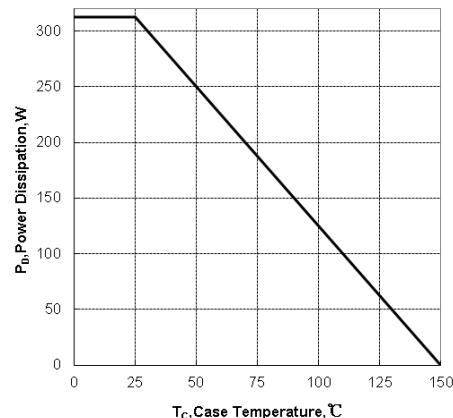
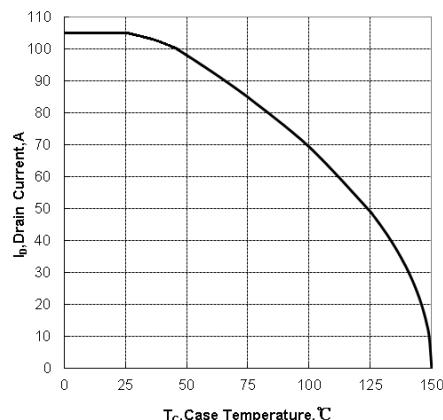
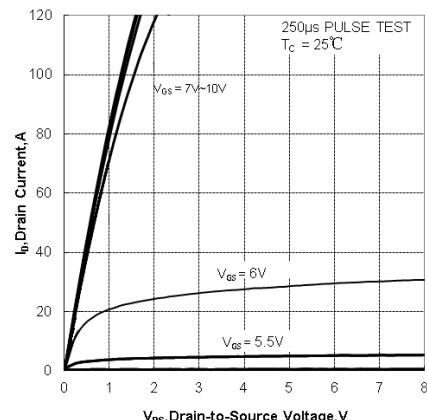
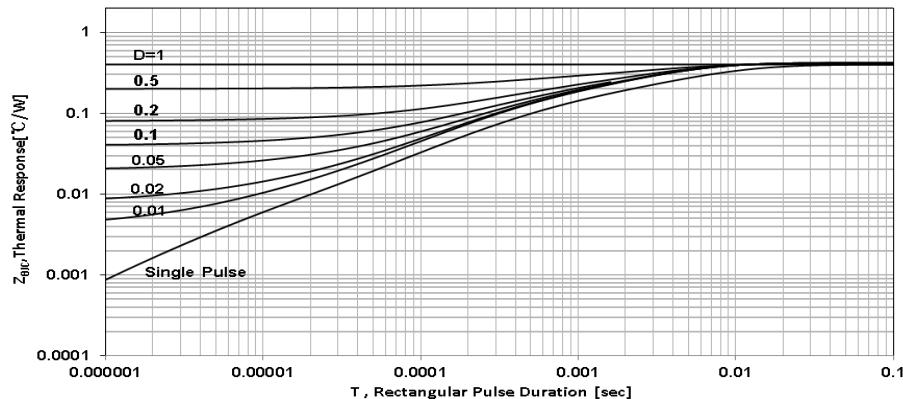
Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time	V _{GS} =10V, R _G =2.2Ω V _{DD} =98V, I _D =62A	--	42.4	--	ns
t _r	Rise Time		--	204	--	
t _{d(OFF)}	Turn-Off Delay Time		--	82	--	
t _f	Fall Time		--	29	--	
Q _g	Total Gate Charge	V _{GS} =10V, V _{DD} =75V I _D =62A	--	137.6	--	nC
Q _{gs}	Gate to Source Charge		--	42.8	--	
Q _{gd}	Gate to Drain ("Miller")Charge		--	49.9	--	

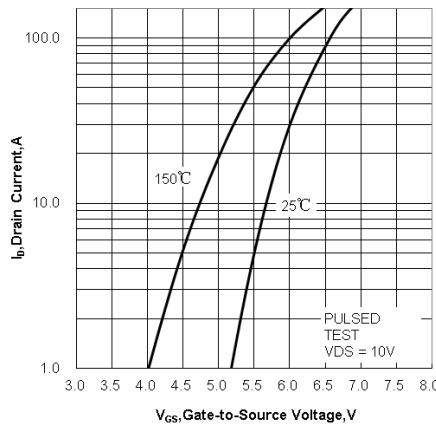
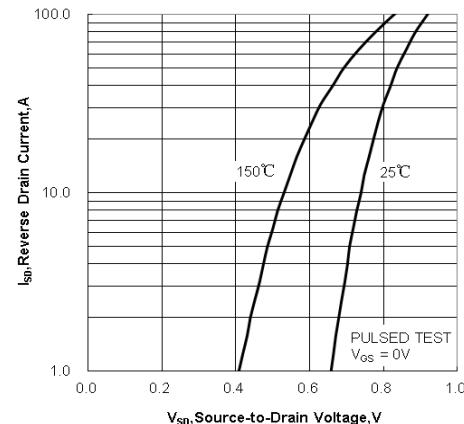
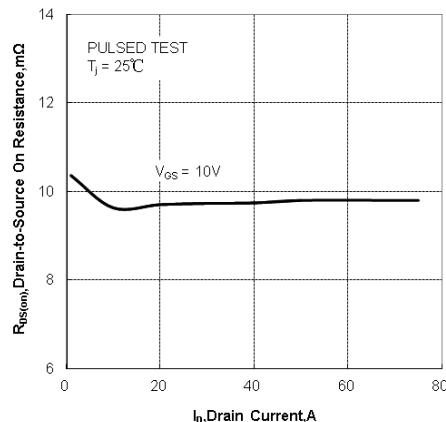
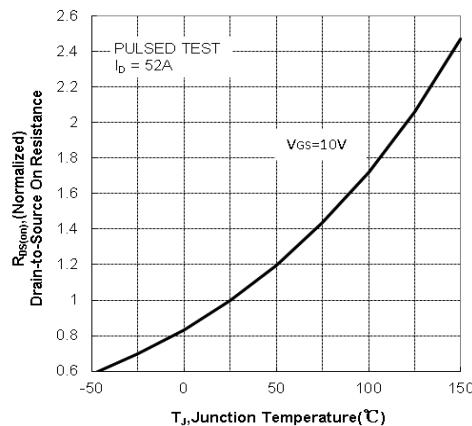
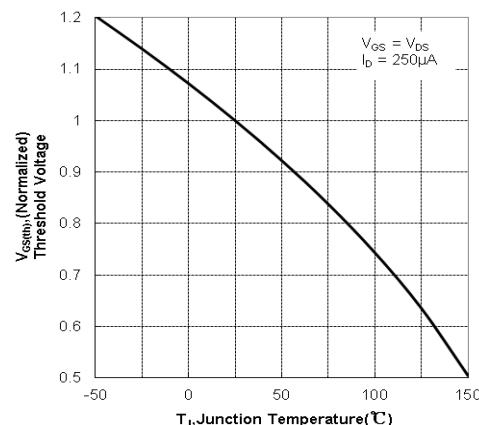
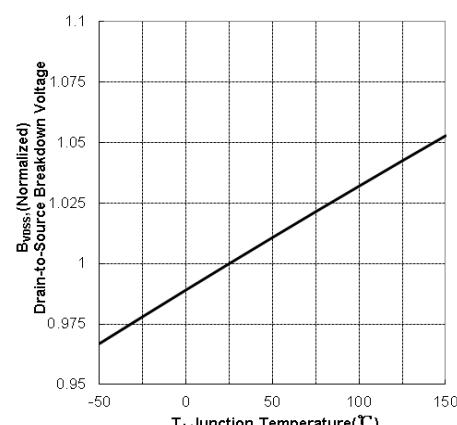
Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I _S	Continuous Source Current (Body Diode)		--	--	105	A
I _{SM}	Maximum Pulsed Current (Body Diode)		--	--	420	A
V _{SD}	Diode Forward Voltage	I _S =75A, V _{GS} =0V	--	--	1.2	V
t _{rr}	Reverse Recovery Time	I _S =62A, T _j = 25 °C dI _F /dt=100A/us,	--	84.4	--	ns
Q _{rr}	Reverse Recovery Charge		--	448	--	nC
I _{RRM}	Reverse Recovery Current		--	10.6	--	A
Pulse width t _p ≤300μs, δ ≤2%						

Symbol	Parameter	Max.	Units
R _{θJC}	Junction-to-Case	0.4	°C/W
R _{θJA}	Junction-to-Ambient	62.5	°C/W

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a2}: L=0.5mH, I_D=60.83A, Start T_j=25 °C

Characteristics Curve:

Figure1. Maximum Forward Bias Safe Operating Area

Figure2. Maximum Power Dissipation vs Case Temperature

Figure3. Maximum Continuous Drain Current vs Case Temperature

Figure4. Typical Output Characteristics

Figure5. Maximum Effective Transient Thermal Impedance, Junction-to-Case


Figure 6. Typical Transfer Characteristics

Figure 7. Typical Body Diode Transfer Characteristics

Figure 8. Drain-to-Source On Resistance vs Drain Current

Figure 9. Normalized on Resistance vs Junction Temperature

Figure 10. Normalized Threshold Voltage vs Junction Temperature

Figure 11. Normalized Breakdown Voltage vs Junction Temperature

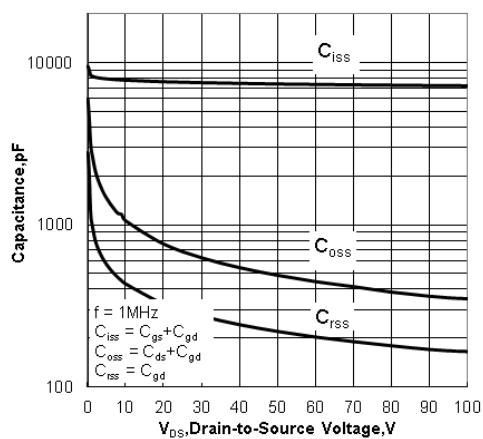


Figure12. Capacitance Characteristics

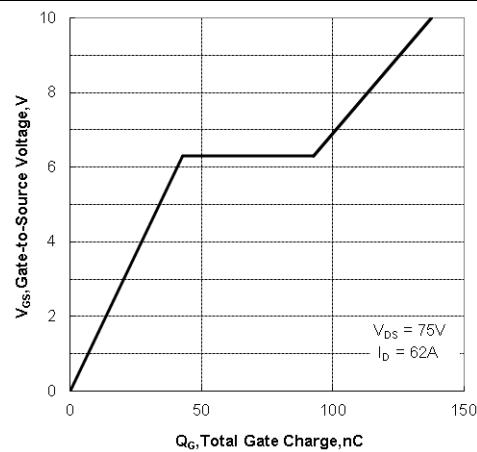


Figure13. Typical Gate Charge vs Gate to Source Voltage

Test Circuit and Waveform

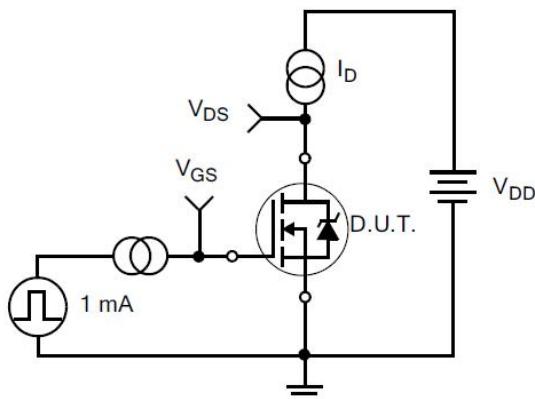


Figure 14. Gate Charge Test Circuit

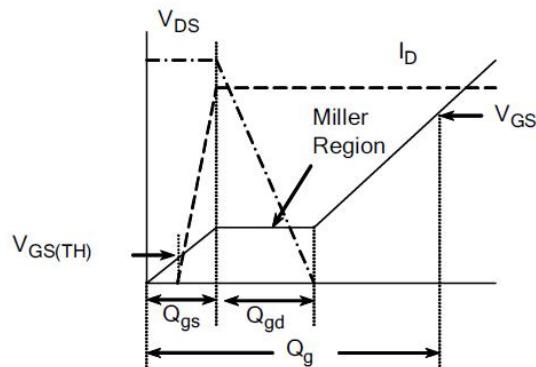


Figure 15. Gate Charge Waveforms

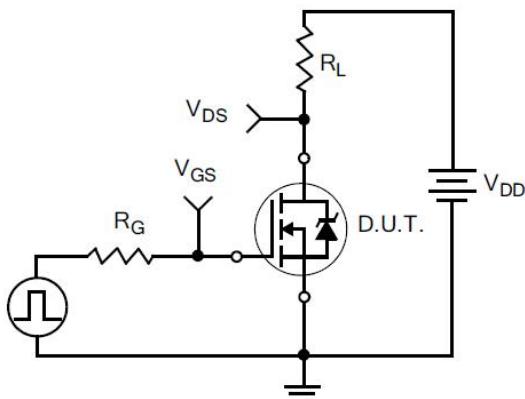


Figure 16. Resistive Switching Test Circuit

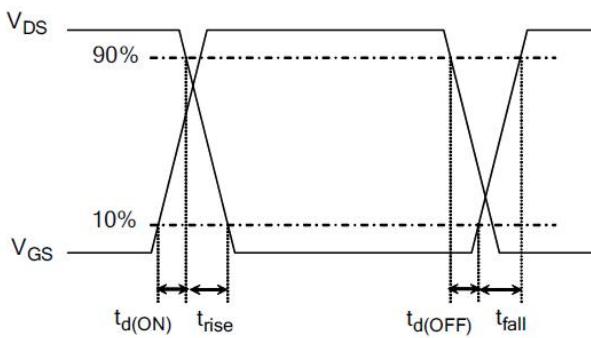


Figure 17. Resistive Switching Waveforms

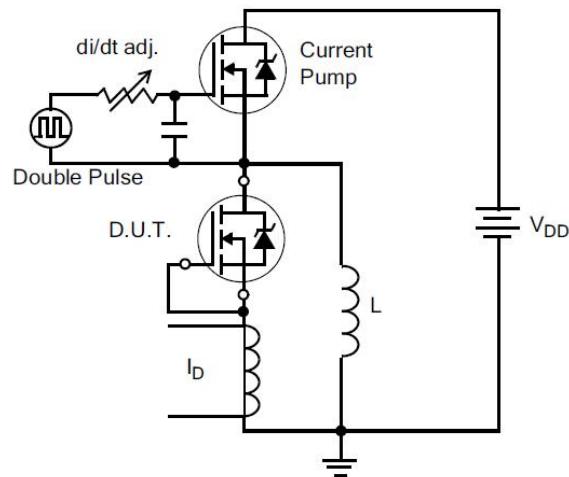


Figure 18. Diode Reverse Recovery Test Circuit

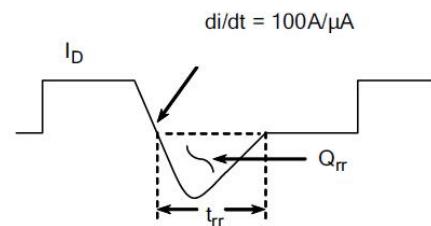


Figure 19. Diode Reverse Recovery Waveform

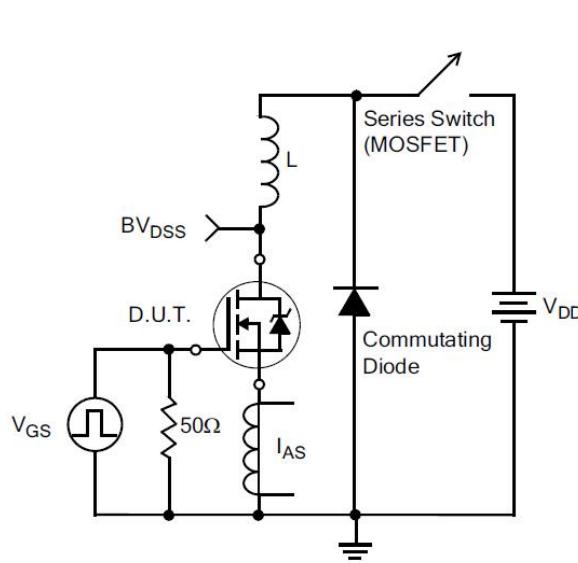


Figure 20. Unclamped Inductive Switching Test Circuit

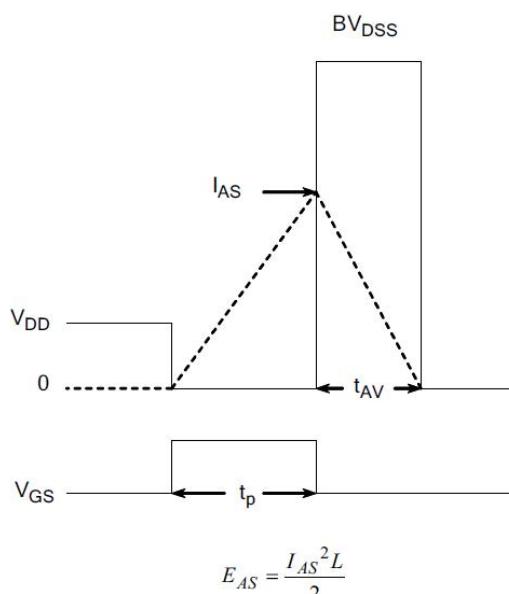
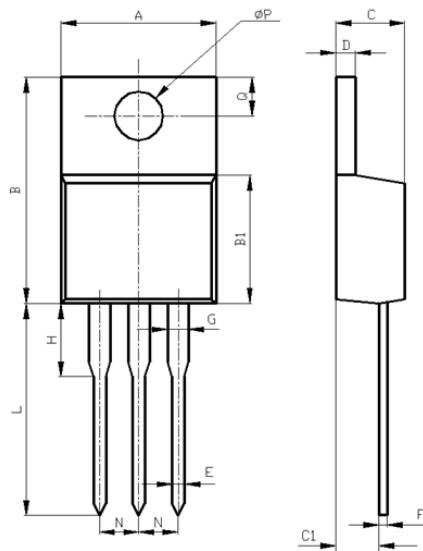


Figure 21. Unclamped Inductive Switching Waveform

Package Information:


Items	Values(mm)	
	MIN	MAX
A	9.60	10.6
B	15.0	16.0
B1	8.90	9.50
C	4.30	4.80
C1	2.30	3.10
D	1.20	1.40
E	0.70	0.90
F	0.30	0.60
G	1.17	1.37
H	2.70	3.80
L*	12.6	14.8
N	2.34	2.74
Q	2.40	3.00
Φ P	3.50	3.90

*adjustable

TO-220AB Package